# DOCUMENT CHANGE REQUEST

DCR number 613 Changes required for: General

Date: 2010/06/11 Date sent: 2010/06/11

Status: IMPLEMENTED

Originator: Jean-Laurent BOUTEAUX

Organisation: CNES

| | |
|---|---|
| Title: | Connectors Electrical Rectangular Non-Removable Solder Bucket PCB and Wire-Wrap Contacts |

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|---|---|---|---|
| Number: | 3401/001 | Issue: | 4 |

Other documents affected:

3401/081-3

Page:

Page 38 Â§ 4.2.2

Paragraph:

Page 38 Â§ 4.2.2

Original wording:

Proposed wording:

Add an appendix:
"Description of deviation"
"Â§ 9.1.1.3 Contact Resistance: 20% Contact Resistance Test may be omitted for solder bucket,PCB and Wire-Wrap socket contacts,provided that a 100% Contact Capability Test and a low level Contact Resistance test by sampling(10 part per batch)are performed in accordance with the SOURIAU PID requirements. The results of the Contact Resistance Test shall be considered for PDA

Justification:

Contact Capability Test performed at 100%

Attachments:

N/A

Modifications:

The original Proposed Wording of Change detailing the content of the new appendix for Souriau in 3401/001 & 3401/081 shall be replaced by the following:

Add new appendix:
AGREED DEVIATIONS FOR SOURIAU (F)

3401/001:
.........................
Items Affected
Para. 4.2.2, Deviations from Final Production Tests (Chart II)

Description of Deviations
Para. 9.1.4, Electrical Measurements at Room Temperature:
For solder bucket, PCB and wire-wrap contacts, Low Level Contact Resistance and Rated Current Contact Resistance measurements, performed in accordance with Table 2 of the Detail Specification, may be omitted provided that Low Level Contact Resistance measurements are performed on 10 contacts per contact batch, in accordance with the Souriau PID requirements. The results of the Low Level Contact Resistance measurements shall be considered for PDA.
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3401/081:
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Items Affected
Para. 4.2.2, Deviations from Final Production Tests (Chart II(b))

Description of Deviations
Para. 9.1.4, Electrical Measurements at Room Temperature:
For all contacts, Low Level Contact Resistance and Rated Current Contact Resistance measurements, performed in accordance with Table 2 of the Detail Specification, may be omitted provided that Low Level Contact Resistance measurements are performed on 10 contacts per contact batch, in accordance with the Souriau PID requirements. The results of the Low Level Contact Resistance measurements shall be considered for PDA.

Justification
SOURIAU justifies its request to carry out only the low level contact resistance test on a sampling of 10 parts per batch for the final production tests because for each manufacturing batch of contacts we have:
- CofC of raw material
- a test report of plating with thickness measurements, plating porosity test and adherence test .
- dimensional check
- crimping capability test
- for socket contacts “Contact Capability test at 100%”

Approval signature:

Date signed:

2010-06-11